

# **SQ3000** 3D AOI

**Automated Optical Inspection** 



## **Nordson TEST & INSPECTION**

Founded in 1954, Nordson Corporation is a market leading industrial technology company with annual revenues of over \$2.1 billion and more than 7,500 employees worldwide.

Nordson TEST & INSPECTION offers its SMT & Semiconductor customers a robust product portfolio, including Acoustic, Optical and both Manual and Automated X-ray Inspection systems, X-ray Component Counting systems and Semiconductor measurement sensors.

Nordson TEST & INSPECTION is uniquely positioned to serve its customers with best-in-class precision technologies, passionate sales and support teams, global reach, and unmatched consultative applications expertise.





### Proprietary Advanced Technology

Optical Inspection & Metrology







## WS Products

### Improve Your Yields

Semiconductor Metrology Sensors

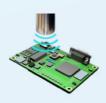




## **AMI** Products

### Qualify Your Design

Acoustic Inspection

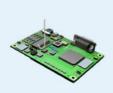




## BT Products

### Test Your Design

Bondtesters

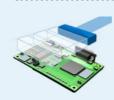




## **AXI** Products

#### High Speed High Flexibility

Automated X-ray Inspection





## MXI Products

## Making the Invisible, Visible

Manual X-ray Inspection





## **AXM** Products

## Measuring the Invisible

Automated X-ray Metrology





## CC Products

#### Maximize Efficiency

X-ray Component Counting





## XRT Products

### High Speed High Resolution

X-ray Technologies



# The Ultimate in Speed & Accuracy

## 3D AOI

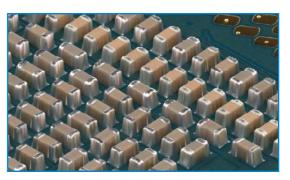
The SQ3000 3D AOI solution is loaded with powerful tools that cover inspection and measurement for AOI applications.



High Precision Accuracy with Multi-Reflection Suppression® (MRS®) Sensor Technology.

# MRS Sensor Solutions for Metrology, Assembly, and Process Improvement

The SQ3000 with MRS technology has multiple sensor options to meet even the most demanding applications. Nordson TEST & INSPECTION has advanced the proprietary Multi-Reflection Suppression (MRS) sensor to an even finer resolution. The Ultra-High Resolution MRS sensor enhances the SQ3000 3D AOI platform, delivering superior inspection performance, ideally suited for the 0201 metric process and microelectronic applications where an even greater degree of accuracy and inspection reliability is critical.



Packaging SMT

### **Large Board Capability**

The SQ3000™ X supports large boards up to 710 x 610 mm, and is capable of inspecting the most demanding assemblies at production speed without compromising on measurement accuracy and repeatability.









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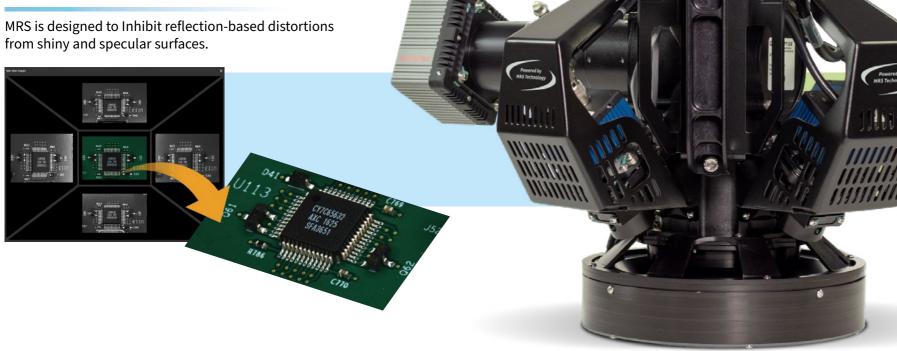
# **Multi-Reflection Suppression®**

# (MRS®) Sensor Technology

The SQ3000 is powered by CyberOptics' breakthrough 3D sensing technology comprising four multi-view 3D sensors and a parallel projector delivering metrology grade accuracy at production speed.

### **Reflection based distortions**

from shiny and specular surfaces.



Nordsons' unique sensor architecture simultaneously captures and transmits multiple images in parallel while proprietary 3D fusing algorithms merge the images together. The result is ultra-high quality 3D images and high-speed inspection.

SQ3000 offers unmatched accuracy with the revolutionary MRS technology by meticulously identifying and rejecting reflections caused by shiny components and reflective solder joints.

#### **MULTIPLE MRS SENSOR OPTIONS**

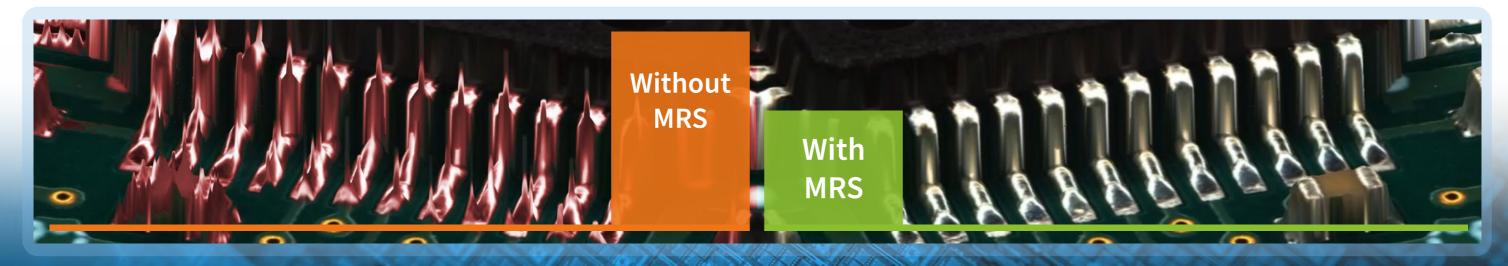
Standard **MRS Sensor** 

High Speed

High Resolution

**Ultra High** Resolution

Effective suppression of multiple reflections is critical for accurate measurement making MRS an ideal technology solution for a wide range of applications including those with very high quality requirements.



# **Enable Smarter, Faster Inspection**

The multi-award winning SQ3000 AOI software is a more powerful yet extremely simple software suite designed with an intuitive interface and multi-touch control with 3D image visualization tools.

## **Ultra-fast programming capabilities**

Bring the ease-of-use to a completely new level and significantly speed setup, simplifie the process, reduce training efforts and minimize operator interaction – all saving time and cost.

## **Enable smarter, faster inspection**

Speed programming and performance with AI<sup>2</sup> (Autonomous Image Interpretation) technology for set-up in <13 minutes with a data-rich, preloaded library and automated scripts that collect and update models all on their own.

Inspect the most comprehensive list of features and identify the widest variety of defects. Al<sup>2</sup> offers precise discrimination with just one panel inspection making it the perfect solution for highmix and high-volume applications.

#### $AI^2$

Al<sup>2</sup> technology is all about keeping it simple no parameters to adjust or algorithms to tune. you don't need to anticipate defects or pre-define variance. Al<sup>2</sup> does it all for you. Powered by a datarich, pre-loaded library and automated scripts that collect and update models all on their own.



With Al<sup>2</sup>, you have the power to inspect the most comprehensive list of features and identify the widest variety of defects. Al<sup>2</sup> offers precise discrimination with just one panel inspection making it a perfect solution for high-mix and high volume applications.



Failed Model.



Passed Model

## **Faster, Highly Accurate CMM Suite**

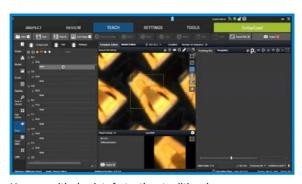
Nordson Software Solution provides our customers and partners the best added-value for inspection and measurement in electronics manufacturing.

### **CyberCMM software suite**

CyberCMM™, a comprehensive software suite of coordinate measurement tools, provides highly accurate, 100% metrology-grade measurement on all critical points much faster than a traditional CMM, including coplanarity, distance, height and datum X, Y to name a few. A fast and easy set-up can be performed with the world's first in-line CMM system for programming complex applications as compared to slow, engineering resource-intensive set-ups that typically requires multiple adjustments with traditional coordinate measurement machines (CMMs).





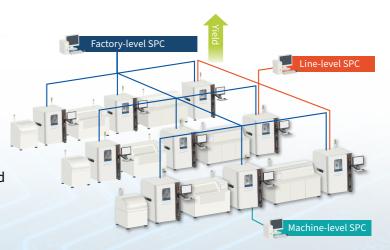


Measure critical points faster than traditional measurement systems.

## Fast, scalable SPC solution

CyberReport™ offers full-fledged machine to factory level SPC capability with powerful historical analysis and reporting tools. The software delivers complete traceability for effective process verification and yield improvement.

CyberReport is designed for simple set-up and intuitive use, while simultaneously delivering scalability, fast charting, and an extremely compact database size.



# **High End Applications**

The SQ3000 3D AOI offers unmatched accuracy with the revolutionary Multi-Reflection Suppression (MRS) technology. Effective suppression of multiple reflections is critical for accurate measurement, making MRS an ideal technology solution for a wide range of applications including those with very high quality requirements.





Fine pitch component inspection. BGA solder ball inspection, diameter measurement, uniformity. BGA coplanarity inspection.





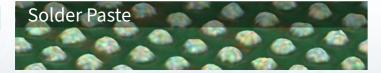
Backlight. Five point & solder paste inspection. Pad Gap inspection. Warpage corpenarity, Illumination Intensity & Adhesive Squeeze out measurements. Dye chip out.





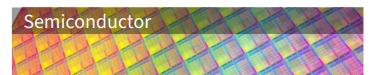
Pin inspection, True position, Inspection on dispensed material, Inspecting dispensed patterns.





Tight area, Off water bridging, Speed and accuracy, Jet print paste, Type 4 paste.







Highly reflective dye, Wirebond, Ribbons, Ball bond, Wirebonding and wedgebond inspection, Wirebond loop height of wire bond, Cornerfill/Underfill inspection.





Microelectronics, Fast and accurate inspection with low false calls, Fast programming, Speed and Accuracy, Quick programming.





Tighter tolerance, Higher demand for accuracy, Small components, More micro electronics, Conformal coating, Life Critical.





Component Verification, Counterfeit part detection, High map & Point cloud output capabilities, Adhesive & epoxy inspection.





Metal modules that have cavities, Suberate & Critical inspection on highly reflective material, Wire bond and ribbon inspection.





Tuning forks, connector, True position for key features, True position for key component for high precision placement, Smaller Modules, Critical pin inspection

# **Specifications**

Inspection Capabilities	Standard MRS Sensor	High-Speed MRS Sensor	High-Resolution MRS Sensor	Ultra-High Resolution MRS Sensor
Inspection Speed	40 cm²/sec (2D+3D)	50 cm <sup>2</sup> /sec (2D+3D)	20 cm²/sec (2D+3D)	15 cm²/sec (2D+3D)
Minimum Component Size	0402 mm (01005 in.)		0201 mm (008004 in.)	
PCB Size	SQ3000: Minimum: 50 x 50 mm (2 x 2 in.); Maximum: 510 x 510 mm (20 x 20 in.) SQ3000-X: Minimum: 50 x 120 mm (2 x 4.7 in.); Maximum: 710 x 610 mm (27.9 x 24 in.)			
Component Height Clearance	Top: 50 mm ; Bottom: 30mm			
PCB Thickness	0.3 - 5 mm			
Component Types Inspected	Standard SMT (chips, J-lead, gull-wing, BGA, etc.), through-hole, odd-form, clips, connectors, header pins, and more			
Component Defects	Missing, polarity, tombstone, billboard, flipped, wrong part, gross body and lead damage, and more			
Solder Joint and Other Defects	Gold finger contamination, excess solder, insufficient solder, bridging, through-hole pins			
3D Measurement Inspection	Lifted Lead, package coplanarity, polarity dimple and chamfer identification			
Measurement Gage R&R	<10% @ ±3σ (±80 μm process tolerance)			
Z Height Accuracy	1 μm on certification target			
Z Measurement Range	6 mm at spec, 24 mm capability		3 mm at spec, 8 mm capability	
Vision System & Technology				
Imagers	Multi-3D sensors			
Resolution	Sub 10 μm		7 μm	
Field of View (FOV)	36 x 30 mm	36 x 36 mm	26 x 26 mm	21 x 21 mm
Image Processing	Autonomous Image Interpretation (AI <sup>2</sup> ) Technology, Coplanarity and Lead Measurement			
Programming Time	<13 minutes (for established libraries)			
CAD Import	Any column-separated text file with ref designator, XY, Angle, Part no info; Valor process preparation			
System Specifications				
Machine Interface	SMEMA, RS232 and Ethernet			
Power Requirements	100-120 VAC or 220-240 VAC, 50/60 hz, 10-15 amps			
Compressed Air Requirements	5.6 Kgf/cm² to 7.0 Kgf/cm² (80 to 100 psi @ 4 cfm)			
System Dimensions	SQ3000: 110 x 127 x 139 cm (W x D x H) • SQ3000-X: 134 x 139 x 139 cm (W x D x H)			
Weight	SQ3000: ≈965 kg (2127 lbs.) • SQ3000-X: ≈1242 kg (2738 lbs.)			
Options				717171
	Barcode Reader, Rework station, SPC Software, Alignment Target SQ3000™ D (Dual Lane), and SQ3000™ DD (Dual Lane - Dual Sensor) models available			

For more information, speak with your Nordson representative or contact your Nordson regional office

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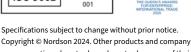
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